

Title (en)

METHOD FOR MAKING A HEAT CONDUCTION-COOLED ELECTRONIC CARD

Title (de)

HERSTELLUNGSVERFAHREN EINER ELEKTRONISCHEN LEITERPLATTE MIT WÄRMEABLEITUNG

Title (fr)

PROCEDE DE FABRICATION D'UNE CARTE ELECTRONIQUE A REFROIDISSEMENT PAR CONDUCTION THERMIQUE

Publication

**EP 0811309 A1 19971210 (FR)**

Application

**EP 96902303 A 19960130**

Priority

- FR 9600150 W 19960130
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Abstract (en)

[origin: WO9626631A1] Methods for making thermally cooled electronic cards are disclosed. The method comprises providing a card (2, 3i) of any kind to be covered with a rigid heat sink (1) shaped to fit and attached to the card (2, 3i), and forming said heat sink (1) in such a way that it fits as closely as possible the shape of the printed circuit (2) having components (3i) on one or both sides thereof, whereby the surface thermal coupling between the sink (1) and the card (2, 3i) may be increased, by means of an optical sensor which preferably operates with a laser beam. Such a heat sink may thus be manufactured more quickly.

IPC 1-7

**H05K 7/20**; **G05B 19/42**

IPC 8 full level

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Citation (search report)

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